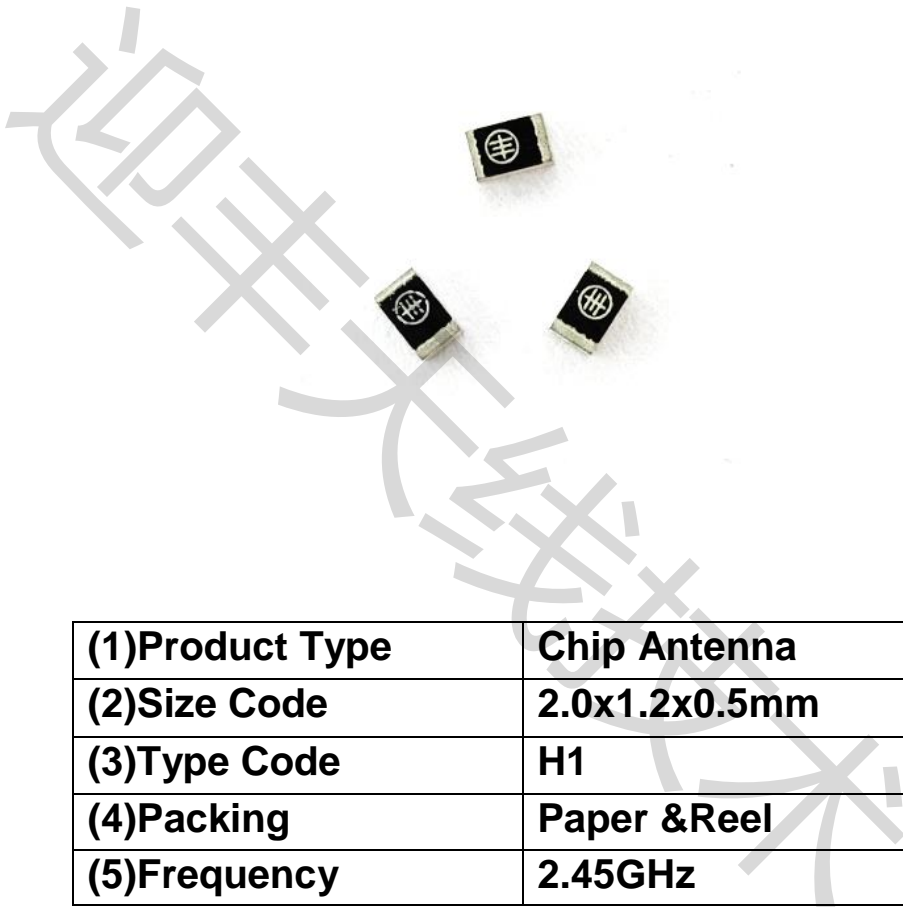


# 2.0X1.2X0.5 (mm) WiFi/Bluetooth Ceramic Chip Antenna (YF2012H1) Engineering Specification

## 1. Product Number

YF	2012	H1	X	2G45	01
1	2	3	4	5	6



(1)Product Type	Chip Antenna
(2)Size Code	2.0x1.2x0.5mm
(3)Type Code	H1
(4)Packing	Paper &Reel
(5)Frequency	2.45GHz



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Prepared by : **JIEXI**

Designed by : **Jason**

Checked by : **Jason**

Approved by : **MR.FANG**

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**YF2012H1P2G45**

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## 2. Features

- \*Stable and reliable in performances
- \*Low temperature coefficient of frequency
- \*Low profile, compact size
- \*RoHS compliance
- \*SMT processes compatible

## 3. Applications

- \*Bluetooth earphone systems
- \*Hand-held devices when WiFi /Bluetooth functions are needed, e.g., Smart phone.
- \*IEEE802.11 b/g/n
- \*ZigBee
- \*Wireless PCMCIA cards or USB dongle

## 4. Description

Yingfeng chip antenna series are specially designed for WiFi/Bluetooth applications. Based on yingfeng proprietary design and processes, this chip antenna has excellent stability and sensitivity to consistently provide high signal reception efficiency.

## 5. Electrical Specifications (80 x 40 mm<sup>2</sup> ground plane)

5-1. Electrical Table

Characteristics		Specifications	Unit
Outline Dimensions		2.0x1.2x0.5	mm
Working Frequency		2400~2500	MHz
VSWR		2 Max.	
Impedance		50	Ω
Polarization		Linear Polarization	
Gain	Peak	-1.39 (typical)	dBi
	Efficiency	75 (typical)	%



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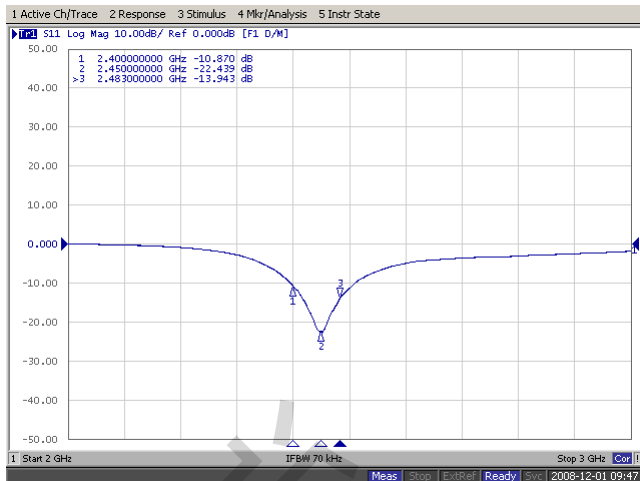
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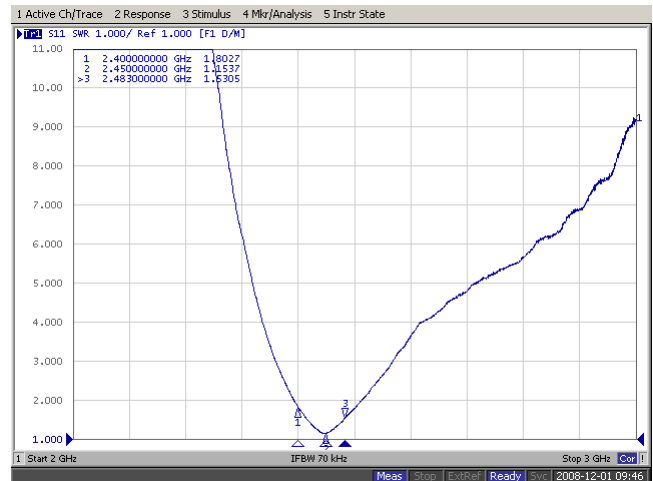
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## 5-2. Return Loss & VSWR

### Return Loss (S<sub>11</sub>)

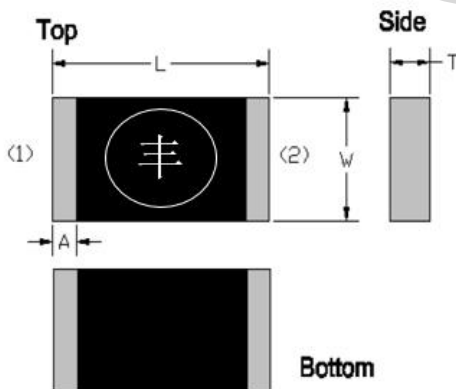


### VSWR(S<sub>11</sub>)



## 6. Antenna Dimensions & Test Board (unit: mm)

### a. Antenna Dimensions



Dimension (mm)	Value
L	2.05+0.15
W	1.20+0.15
T	0.50+0.10
A	0.20+0.10

No.	Terminal Name
1	Feeding/GNG
2	GND/Feeding

P.S : Top & down and left & right side are symmetrical, No direction



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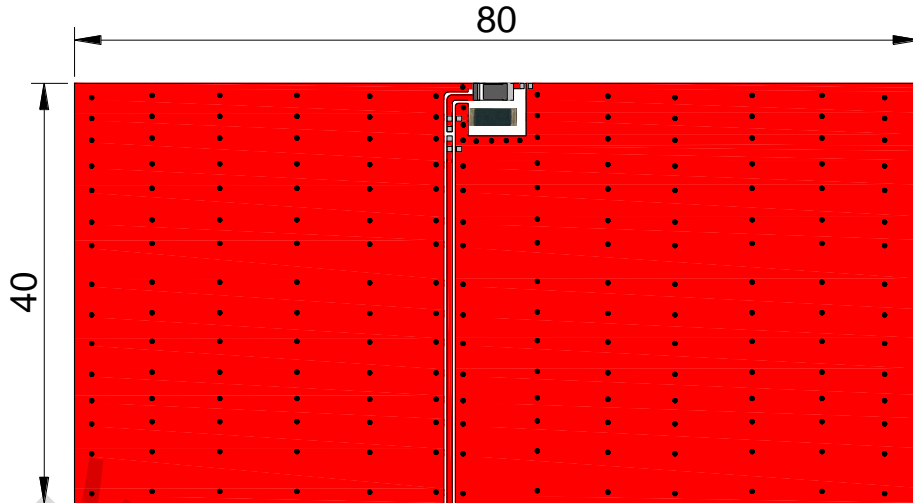
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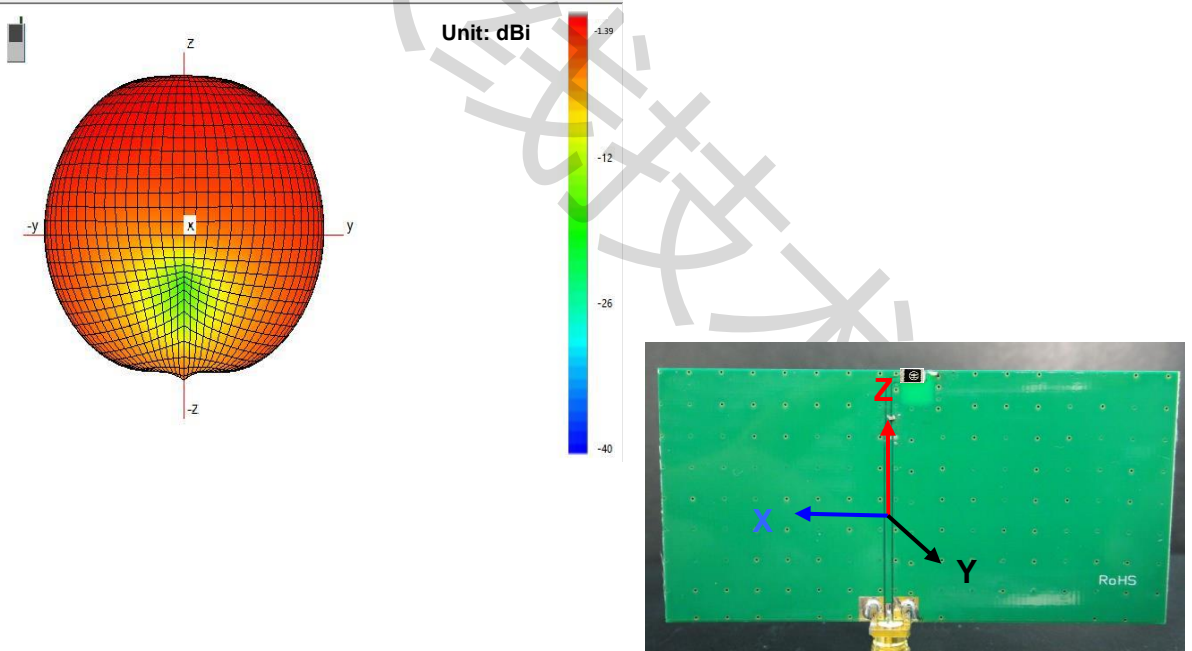
b. Test Board with Antenna



Unit: mm

7. Radiation Pattern (80 x 40 mm<sup>2</sup> ground plane)

7-1. 3D Gain Pattern @2442MHz



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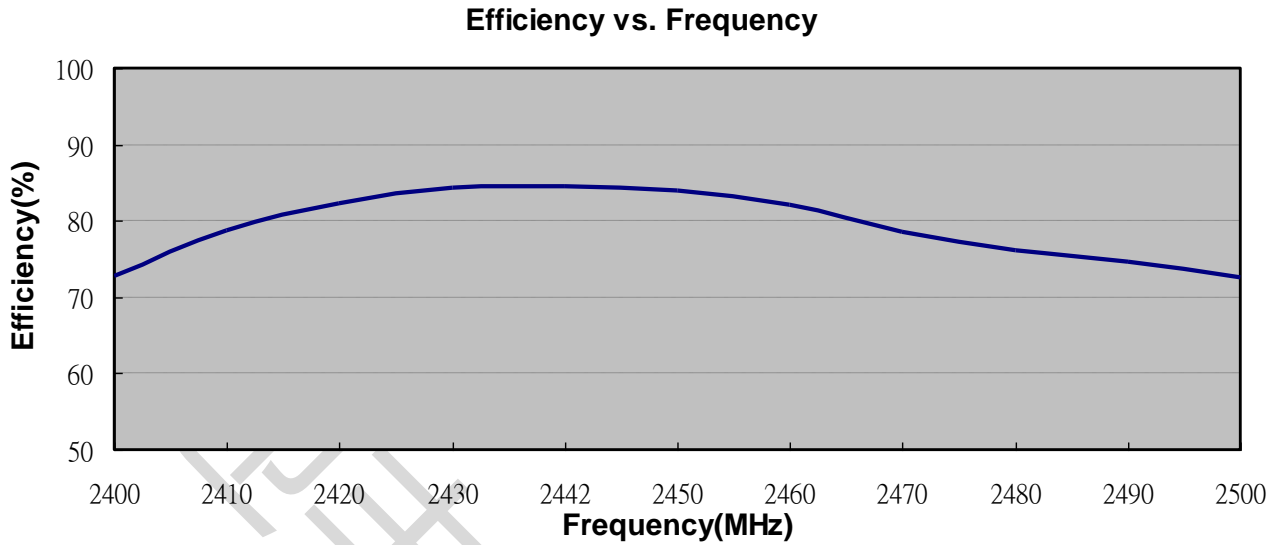
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7-2. 3D Efficiency vs. Frequency



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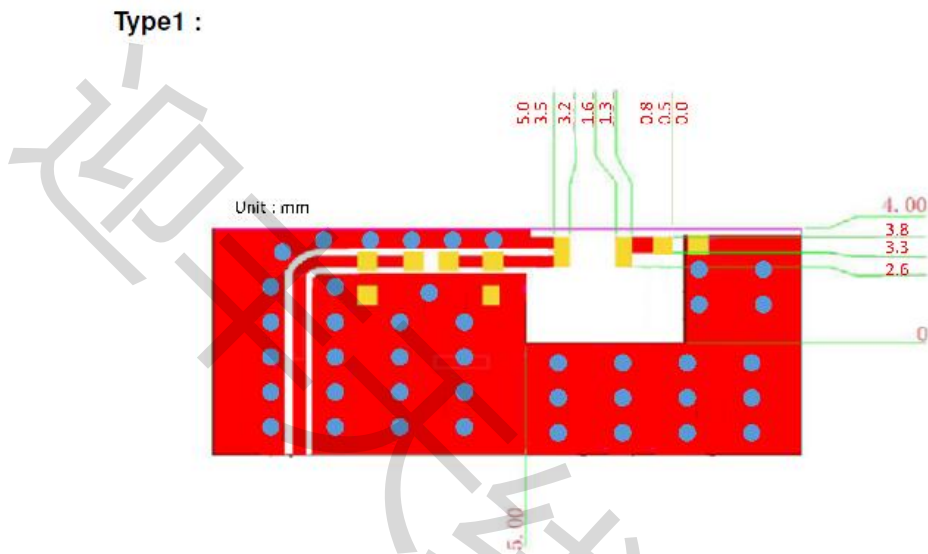
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## 8. Layout Guide

### a. Solder Land Pattern:

Land pattern for soldering (gray marking areas) is as shown below. Depending on Customer's requirement, matching circuit as shown below is also recommended.

### 2). PCB Top View :



Top View



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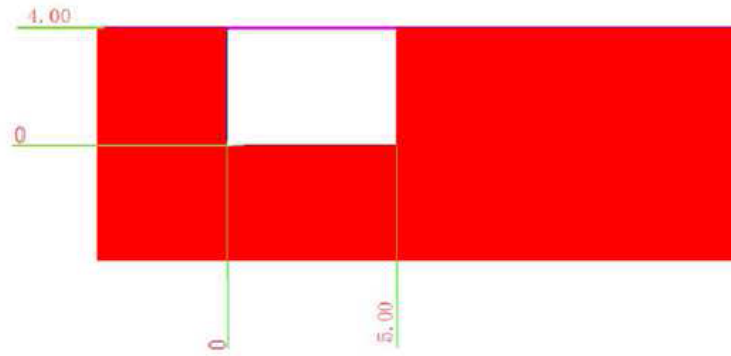
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Unit: mm

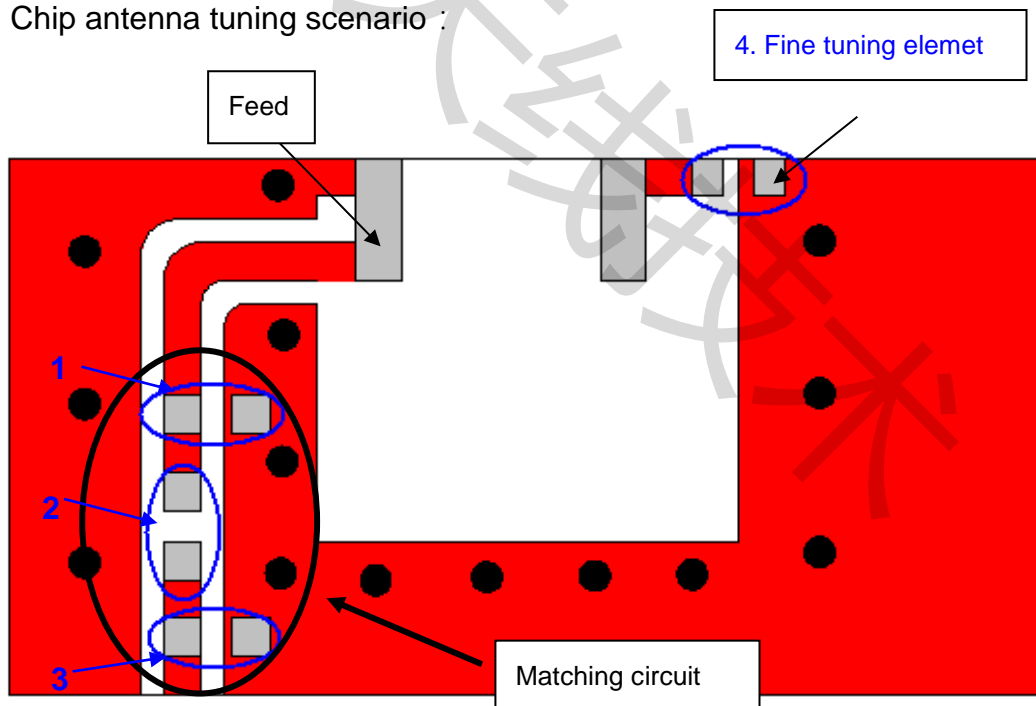


Bottom View

Unit : mm

## 9. Frequency tuning

a. Chip antenna tuning scenario :



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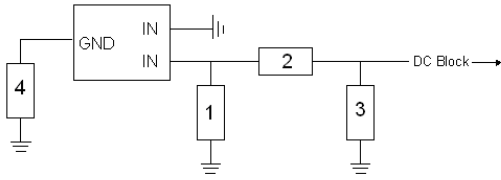
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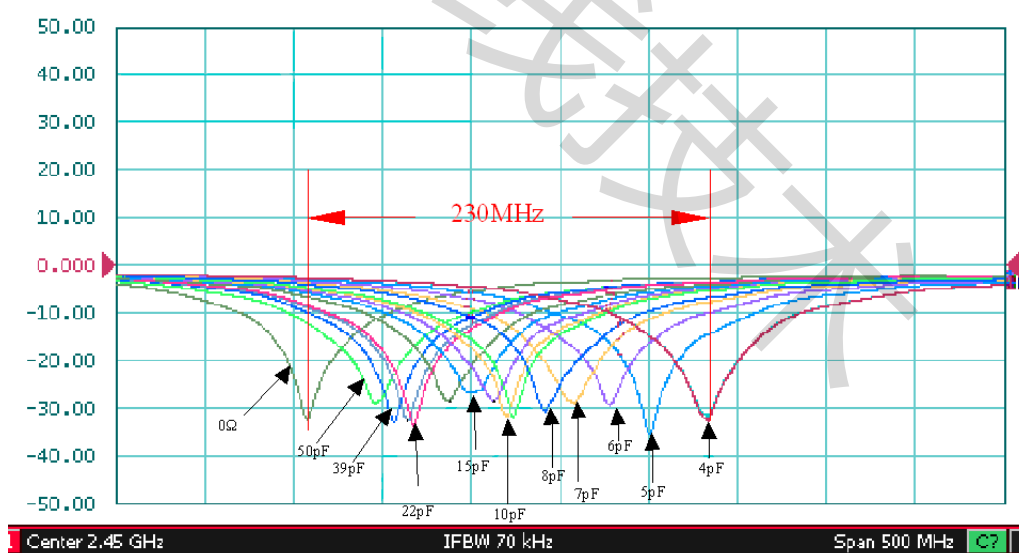
b. Matching circuit : (Center frequency is about 2442 MHz @ 80 x 40 mm<sup>2</sup> ground plane)



System Matching Circuit Component			
Location	Description	Vendor	Tolerance
1	1.2 pF*	Murata (0402)	±0.1 pF
2	10PF*	Murata(0402)	±0.5 PF
3	N/A*	-	-
Fine tuning element 4	10 pF*	Murata (0402)	±0.1 pF

\*Typical reference values which may need to be changed when circuit boards or part vendors are different.

c. Fine tuning element vs. Center frequency



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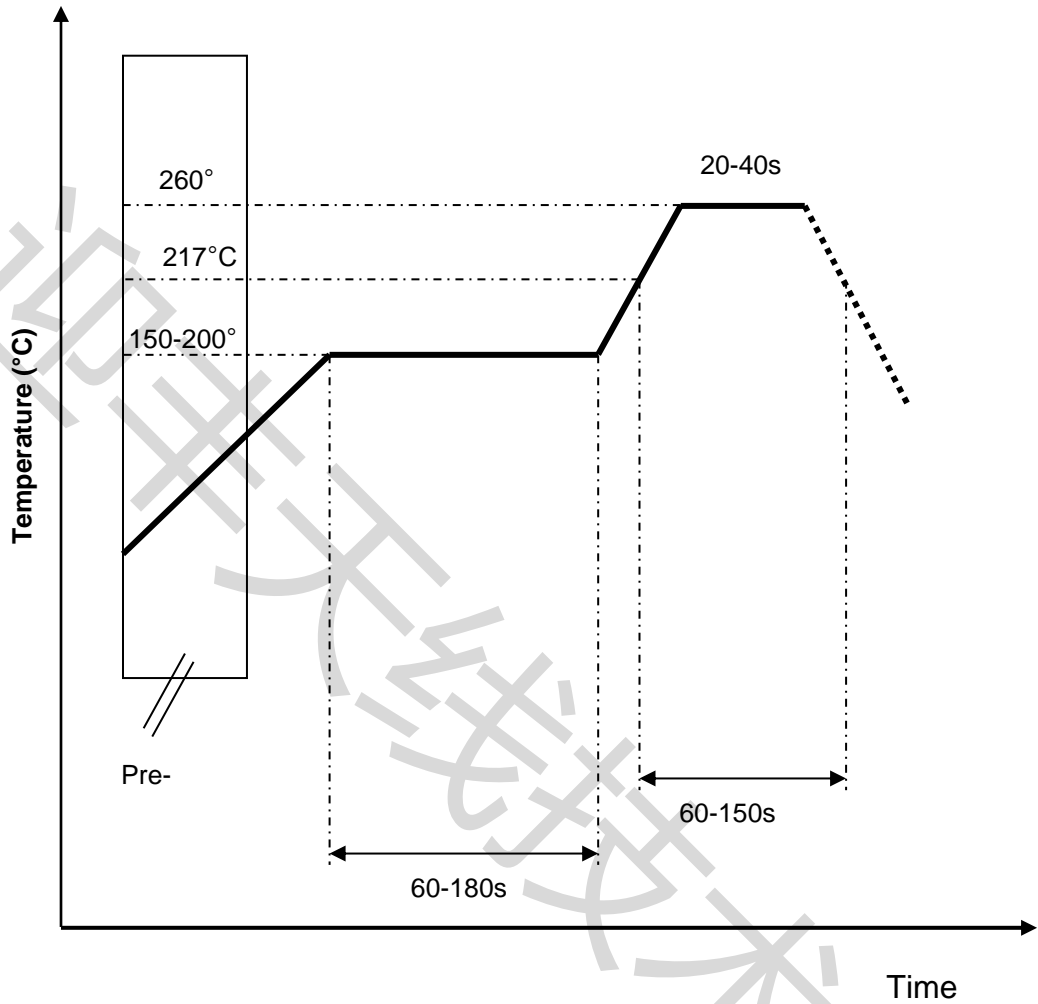
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# 10. Soldering Conditions

a. Typical Soldering Profile for Lead-free Process



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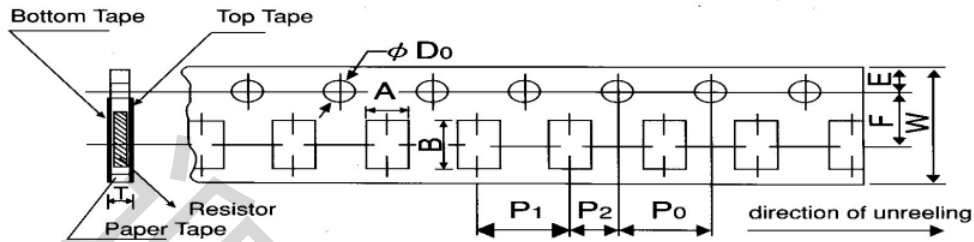
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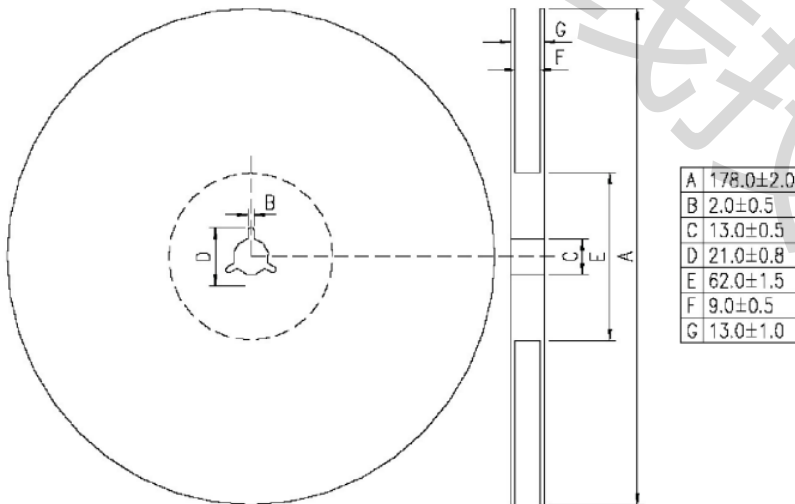
# 11. Packing

- (1) Quantity/Reel: 5000 pcs/Reel
- (2) Plastic tape:



Packing	Style	A	B	W	F	E	P <sub>1</sub>	P <sub>2</sub>	P <sub>0</sub>	D <sub>0</sub>	T
Paper	2012	1.6±0.15	2.4±0.2	8.0±0.2	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	ψ1.5 +0.1 -0	0.84±0.1

## (3) Taping reel dimensions



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## Reliability Table

Test Item	Procedure	Requirements Ceramic Type	Remark (Reference)
Electrical Characterization		Fulfill the electrical specification	User Spec.
Thermal Shock	1. Preconditioning: $50 \pm 10^{\circ}\text{C}$ / 1 hr, then keep for $24 \pm 1$ hrs at room temp. 2. Initial measure: Spec: refer Initial spec. 3. Rapid change of temperature test: $-30^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ ; 100 cycles; 15 minutes at Lower category temperature; 15 minutes at Upper category temperature.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 107
Temperature Cycling	1. Initial measure: Spec: refer Initial spec. 2. 100 Cycles ( $-30^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ ), Soak Mode=1 (2 Cycle/hours). 3. Measurement at $24 \pm 2$ Hours after test condition.	No Visible Damage. Fulfill the electrical specification.	JESD22 JA104
High Temperature Exposure	1. Initial measure: Spec: refer Initial spec. 2. Unpowered; 500hours @ $T=+85^{\circ}\text{C}$ . 3. Measurement at $24 \pm 2$ hours after test.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108
Low Temperature Storage	1. Initial measure: Spec: refer Initial spec. 2. Unpowered: 500hours @ $T= -30^{\circ}\text{C}$ . 3. Measurement at $24 \pm 2$ hours after test.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108
Solderability (SMD Bottom Side)	Dipping method: a. Temperature: $235 \pm 5^{\circ}\text{C}$ b. Dipping time: $3 \pm 0.5\text{s}$	The solder should cover over 95% of the critical area of bottom side.	IEC 60384-21/22 4.10
Soldering Heat Resistance (RSH)	Preheating temperature: $150 \pm 10^{\circ}\text{C}$ . Preheating time: 1~2 min. Solder temperature: $260 \pm 5^{\circ}\text{C}$ . Dipping time: $5 \pm 0.5\text{s}$	No Visible Damage.	IEC 60384-21/22 4.10
Vibration	5g's for 20 min., 12 cycles each of 3 orientations Note: Use 8"x5" PCB .031" thick 7 secure points on, one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz.	No Visible Damage.	MIL-STD-202 Method 204
Mechanical Shock	Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks) Peak value: 1,500g's Duration: 0.5ms Velocity change: 15.4 ft/s Waveform: Half-sine	No Visible Damage.	MIL-STD-202 Method 213
Humidity Bias	1. Humidity: 85% R.H., Temperature: $85 \pm 2^{\circ}\text{C}$ . 2. Time: $500 \pm 24$ hours. 3. Measurement at $24 \pm 2$ hrs after test condition.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 Method 106



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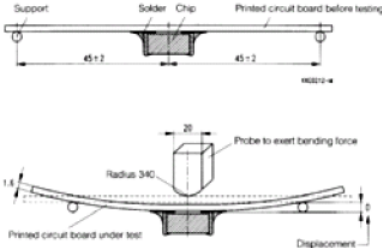
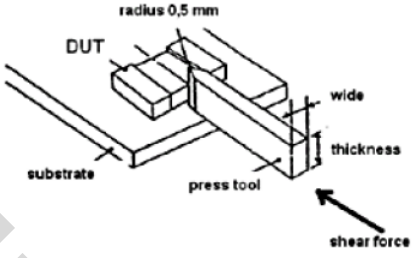
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<b>Board Flex (SMD)</b>	<p>1. Mounting method: IR-Reflow. PCB Size (L:100 × W:40 × T:1.6mm)</p> <p>2. Apply the load in direction of the arrow until bending reaches 2 mm.</p> 	No Visible Damage.	AEC-Q200 005
<b>Adhesion</b>	<p>Force of 1.8Kg for 60 seconds.</p> 	No Visible Damage Magnification of 20X or greater may be employed for inspection of the mechanical integrity of the device body terminals and body/terminal junction.	AEC-Q200 006
<b>Physical Dimension</b>	<p>Any applicable method using x10 magnification, micrometers, calipers, gauges, contour projectors, or other measuring equipment, capable of determining the actual specimen dimensions.</p>	In accordance with specification.	JESD22 JB100



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